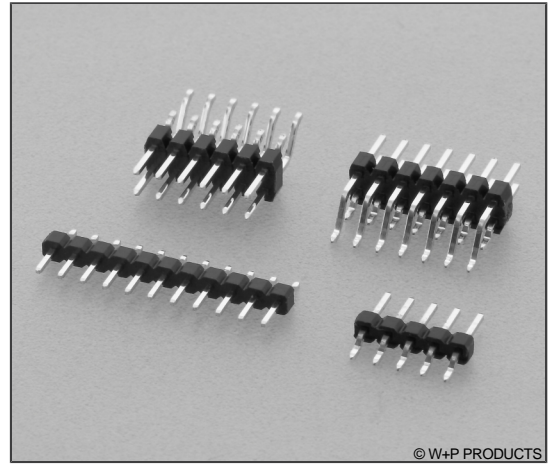


## SMT-Stiftheisen RM 2,00mm, liegend, 1-/2-reihig SMT Pin Headers, 2.00mm Pitch, Horizontal, Single/Double Row

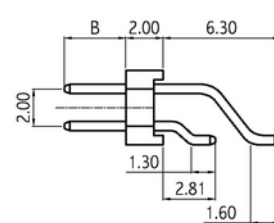
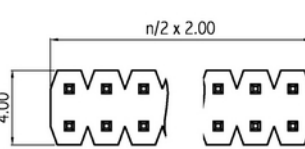
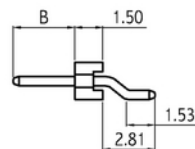
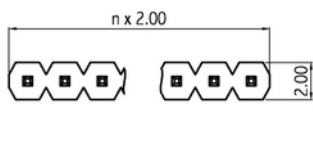
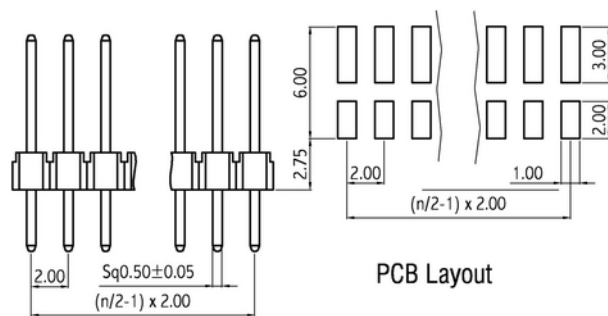
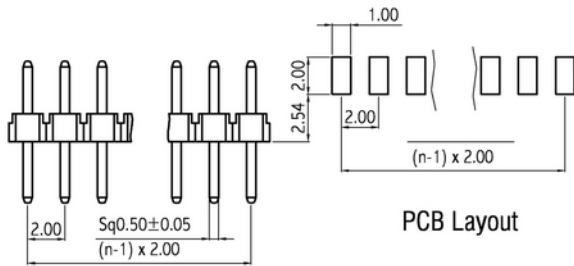
### Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Vierkantstift 0,50mm, Kupferlegierung
Contact Material	0.50mm square pin, copper alloy
Kontaktfläche	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm)
Contact Surface	Acc. to options (see below), over Ni (1.3 ... 2.5µm)
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 500 MΩ
Insulation Resistance	> 500 MΩ
Spannungsfestigkeit	500 V AC
Test Voltage	500 V AC
Nennspannung	250 V AC
Voltage Rating	250 V AC
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40 °C ... +125 °C
Temperature Range	-40 °C ... +125 °C
Verarbeitung	Reflow-Lötverfahren
Processing	Reflow soldering



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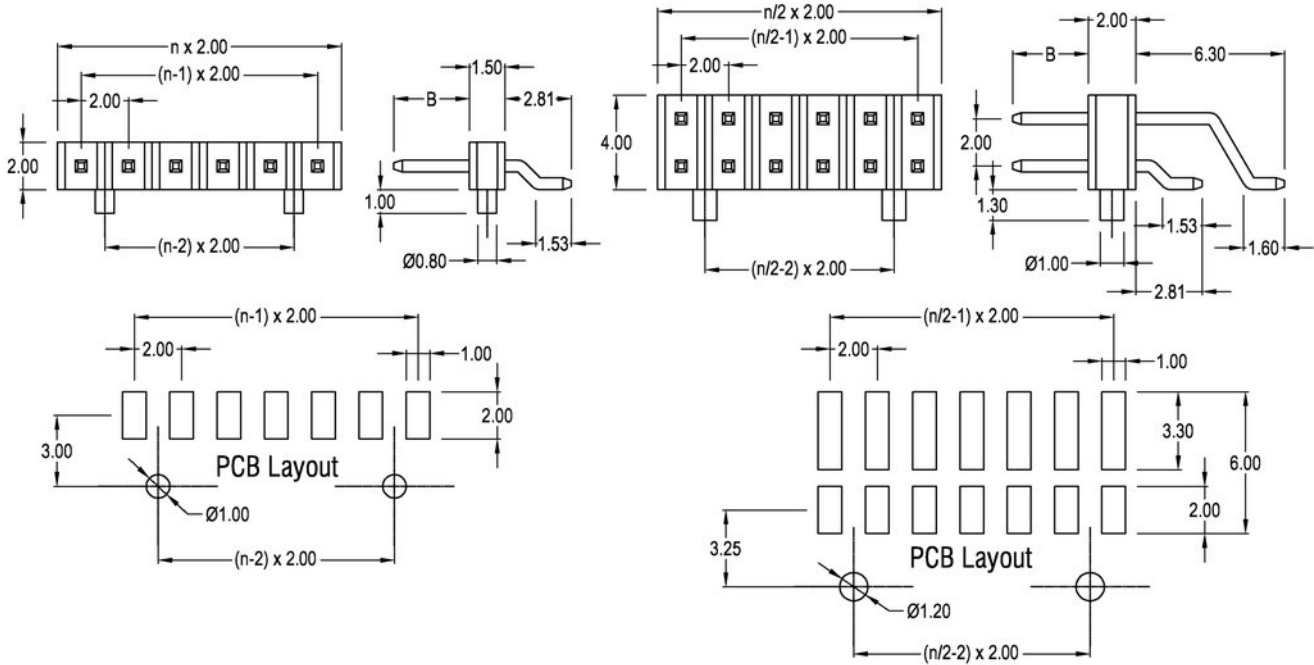
Passende Buchsenleisten:  
Compatible Female Headers:  
**4160 7450 7451 6193** etc.  
Weitere siehe Kapitel B  
Please see ch. B for more



Series	Contacts*	Rows*	Dimensions*	Plating*	Loc. Pegs	Packaging*
<b>7353</b>	<b>36</b> 04-36 Einreihig Single row 06-72 Zweireihig Double row	<b>1</b> 1 Einreihig Single row 2 Zweireihig Double row	<b>10</b> 10 B=3,20mm 11 B=4,45mm 99 Kundenspezifisch Customer-specific	<b>50</b> 00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel Au/Sn Duplex plating	<b>00</b> 00 Ohne Pos.hilfen W/o locating pegs	<b>PPST</b> ST PPST PPTR (Option)

# 7353

SMT-Stiftleisten RM 2,00mm, liegend, 1-/2-reihig  
SMT Pin Headers, 2.00mm Pitch, Horizontal, Single/Double Row



Series	Contacts*	Rows*	Dimensions*	Plating*	Loc. Pegs	Packing*
<b>7353</b>	<b>20</b>	<b>2</b>	<b>10</b>	<b>00</b>	<b>10</b>	<b>ST</b>
	04-36 Einreihig Single row 06-72 Zweireihig Double row	1 Einreihig Single row 2 Zweireihig Double row	10 B=3,20mm 11 B=4,45mm 99 Kundenspezifisch Customer-specific	00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel. Au/Sn Duplex plating	10 Mit Pos.hilfen With locating pegs	ST PPST PPTR (Option)

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** - please replace by your specifications.

**Lieferformen / Packaging Options:**  
**ST** In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads  
**PPST** In Stangen mit P&P-Pads / In tubes with P&P-Pads  
**PPTR (Option)** Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

### Reflow-Lötempfehlung

*Reflow Soldering Recommendation*

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	217 °C
Verweildauer oberhalb $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

*Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).*

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	217 °C
Duration above $T_L$	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

